PRODUCT / PROCESS CHANGE NOTIFICATION

	1. PCN basic data		
1.1 Company	life.augmented	STMicroelectronics International N.V	
1.2 PCN No.		ANALOG MEMS SENSORS/25/15582	
1.3 Title of PCN		ST Manufacturing Reshaping (Analog_HF7/B7_CR200toRST8_All): Qualification of RST8 (France) as new FE Location.	
1.4 Product Category	1	Please refer to the impacted Products List in H7/B7 Technology.	
1.5 Issue date		2025-07-24	

2. PCN Team			
2.1 Contact supplier	2.1 Contact supplier		
2.1.1 Name	KRISZTINA NEMETH		
2.1.2 Phone	+49 89460062210		
2.1.3 Email	krisztina.nemeth@st.com		
2.2 Change responsibility			
2.2.1 Product Manager	Marcello SAN BIAGIO		
2.1.2 Marketing Manager	Salvatore DI VINCENZO, Lionel GRILLO		
2.1.3 Quality Manager	Daniela FAZIO,David MOCELLIN		

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Manufacturing reshaping program	Manufacturing reshaping program	RTS8 (France) as new FE

4. Description of change		
	Old	New
4.1 Description	CR200 (France) as FE Plant	RST8 (France) as FE plant
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact. The products guarantee the same quality and electrical characteristics as per current production.	

5. Reason / motivation for change		
5.1 Motivation	In the frame of ST manufacturing reshaping program (refer to Corporate PCI 15383 - Early Notification), following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing the qualification of RTS8 (France) as FE Location for the impacted Products in H7/B7 Technology. Please note that for products with PIX (polyimide at top passivation), production flow until PIX deposition will be done in ST Rousset, and the step of PIX deposition will be moved to ST Singapore. And on top of Front end transfer, Back end production of selected products in TSSOP14 package will be transferred from Amkor ATP1 to ST Bouskoura. Please be advised that the enclosed list of products and dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available.	
5.2 Customer Benefit	SERVICE CONTINUITY	

6. Marking of parts / traceability of change		
	Traceability of change will be ensured by an internal codification (Finished Good/Type) printed on the carton box label.	

7. Timing / schedule	
7.1 Date of qualification results	2027-04-15
7.2 Intended start of delivery	2027-08-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation	
8.1 Description	

8.2 Qualification report and qualification results	In progress	Issue Date	
--	-------------	---------------	--

9. Attachments (additional documentations)
15582 Public product.pdf 15582 Qualification Plan bicmos7 .zip

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	TSV711ICT	

IMPORTANT NOTICE - PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics - All rights reserved